

In Claims:

A list of the pending claims in the application are provided below:

Claims 1-8: Previously Canceled.

9. (Previously Amended) A semiconductor chip carrier comprising:
a primary substrate;
a metal heat sink plate, whose thermal coefficient of expansion is substantially different from that of said primary substrate, having a first side and an opposing second side where said primary substrate is attached to said first side;
a supplemental substrate being attached to said second side of said metal heat sink plate, wherein said metal heat sink plate is between said primary substrate and said supplemental substrate; and
said supplemental substrate is constructed from a material having a substantially similar coefficient of thermal expansion as that of said primary substrate so that the presence of the supplemental substrate prevents the semiconductor chip carrier from warping.
10. (Original) A semiconductor chip carrier according to claim 9, wherein said supplemental substrate is constructed from a same material as said primary substrate.
11. (Original) A semiconductor chip carrier according to claim 9, wherein said primary substrate is constructed from a material selected from one of Bis-maleimide triazine epoxy, FR4, polyimide, and polytetrafluoroethylene.
12. (Original) A semiconductor chip carrier according to claim 9, wherein said chip carrier is a ball-grid array chip carrier.
13. (Original) A semiconductor chip carrier according to claim 9, wherein said metal heat sink plate consists of a metal selected from one of Cu, Cu-W, Al, and alloys thereof.

14. (Original) A semiconductor chip carrier according to claim 9, wherein said supplemental substrate has a Cu-Ni finish layer.

15. (Original) A semiconductor chip carrier according to claim 9, wherein said supplemental substrate has a cavity exposing a portion of said metal heat sink plate.

Claims 16-19: Previously withdrawn.

20. (Original) A semiconductor chip carrier according to claim 9, wherein said primary substrate comprises a hole forming a die-attach cavity wherein the semiconductor chip is attached to the first side of the metal heat sink plate within the die-attach cavity.